

Abstract of the Disclosure

A package for mounting a plurality of semiconductor chips on one package and minimizing a mounted area, and a method of manufacturing the same is provided.

5 The package includes a film on which a plurality of semiconductor chips are mounted, and the film is folded in a predetermined direction so as to package the plurality of semiconductor chips in one package. The method of manufacturing the package includes mounting a plurality of semiconductor chips on a film and folding the film in a predetermined direction and packaging the plurality of semiconductor chips in one
10 package. The film is folded two or more times such that at least one semiconductor chip is interposed between surfaces of the film. The package can be a tape carrier package (TCP) or a chip-on-film (COF) package.

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